

SUA-110M8A-30x-S372

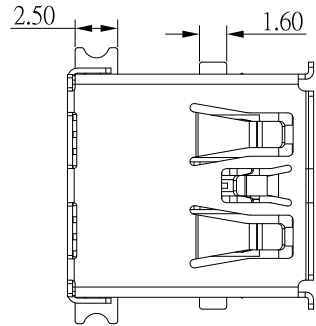
鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"

NOTE:

- 1.MATERIAL:
 - 1.1 Housing: LCP
 - 1.2 Contact: Phosphor Bronze
 - 1.3 Shell: Brass
- 2.Finish:
 - 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
 - 3.1 Current Rate: 1.5 A
 - 3.2 insulator Resistance:100MΩ Min
 - 3.3 Dielectric Strength: 100V AC
 - 3.4 Contact Resistance: 30mΩ Max
 - 3.5 Operation Temperature: -40°C ~ +85°C

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
 CHECKED BY: Jacky Chen
 APPROVED BY: Tony Kao

DATE: 03/23/23
 DATE: 03/23/23
 DATE: 03/23/23

MAT'L
 FINISH
 SCALE: 1 : 1
 SHEET NO. 1 of 1

TITLE: CONNECTOR
 MODLE: USB 3.0 AF SMT 外殼四腳全貼本體長=14.60mm, 板上高7.0 有捲邊 有定位柱
 DWG NO. SUA-110M8A-30x-S372
 PART NO. SUA-110M8A-30x-S372

SIZE: A4
 VER: R

ITEM NO.	DESCRIPTION	DRAWN	DATE